

## CLAIM AMENDMENTS

1 - 29. (canceled)

1           30. (currently amended) A method of making electronic  
2 components each having a chip module with module contacts and an  
3 antenna having antenna contacts, the method comprising the steps  
4 of:

5                 securing a plurality of the chip modules to the inner  
6 face of an elongated module film strip having an outer periphery  
7 projecting past the chip module with the chip modules spaced from  
8 one another on the module film strip at a uniform predetermined  
9 module spacing;

10                securing a plurality of the antennas to an inner face of  
11 an elongated antenna strip with the antennas spaced from one  
12 another by a predetermined distance ~~that is substantially greater~~  
13 ~~than the module spacing; releasably adhering a mounting strip to~~  
14 ~~an outer face of the antenna strip;~~

15                longitudinally subdividing the film strip into film  
16 sections each of which is of a length equal to the predetermined  
17 module spacing and each of which carries a respective chip module;

18                pressing the film sections against the antenna strip such  
19 that the module contacts of each of the chip modules engage and  
20 bear on the antenna contacts of a respective antenna; and

21               bonding the outer periphery of each of the film sections  
22   to the inner face of the antenna strip generally all around each of  
23   the chip modules.

1               31. (previously presented) The method defined in claim  
2   30 wherein the contacts of the chip module or of the antenna have  
3   points so that when pressed against the other contacts they  
4   penetrate the other contacts.

1               32. (previously presented) The method defined in claim  
2   31 wherein the pointed contacts are of pyramidal shape.

1               33. (previously presented) The method defined in claim  
2   32 wherein each pointed contact is formed by a multiplicity of  
3   particles.

1               34. (previously presented) The method defined in claim  
2   33 wherein the particles are nickel-coated diamond particles.

35 - 37. (canceled)

1               38. (previously presented) The method defined in claim  
2   30 wherein the longitudinal subdivision of the module film strip is  
3   carried out before pressing the film sections against the  
4   respective antennas on the antenna strip.

1           39. (currently amended) The method defined in claim 38,  
2 further comprising ~~the step~~, after longitudinally subdividing the  
3 module film strip carrying the modules, the step of  
4           longitudinally spacing the film sections by the distance.

1           40. (previously presented) The method defined in claim  
2 30, wherein the strip sections carrying the modules are pressed  
3 against the antenna strip carrying the antennas before  
4 longitudinally subdividing the module film strip, the longitudinal  
5 subdivision of the module film strip being carried out by removing  
6 pieces of the module film strip between succeeding modules.

1           41. (previously presented) The method defined in claim  
2 30, further comprising the step of  
3           coating the antenna strip with adhesive prior to pressing  
4 the film sections and their respective modules against the antenna  
5 strip.

1           42. (previously presented) The method defined in claim  
2 41 wherein the coating with adhesive is only done to discrete  
3 regions of the antenna strip adjacent the antenna contacts.

1           43. (previously presented) The method defined in claim  
2   42 wherein the discrete regions have a size generally corresponding  
3   to the module spacing.

1           44. (previously presented) The method defined in claim  
2   30, further comprising the steps of  
3           releasably mounting the module film strip on a mounting  
4   strip;  
5           separating the mounting strip from the module film strip  
6   prior to securing thereto the modules; and  
7           releasably securing the modules directly to the mounting  
8   strip at least after longitudinal subdivision of the film strip.

1           45. (previously presented) The method defined in claim  
2   44 wherein the modules are releasably secured to the mounting strip  
3   before longitudinal subdivision of the module film strip and the  
4   longitudinal subdivision of the module film strip is carried out by  
5   removing pieces of the module film strip between the modules.

1           46. (currently amended) The method defined in claim  
2   [[37]] 30, further comprising the step of  
3           rolling up the antenna strip after pressing the film  
4   sections against the antenna strip.

1           47. (currently amended) The method defined in claim 46,  
2 further comprising, ~~the step~~ prior to rolling up the antenna strip,  
3 the step of  
4 inspecting the modules.

1           48. (currently amended) The method defined in claim 47,  
2 further comprising ~~the step~~, after inspecting the modules, the step  
3 of  
4 marking any modules failing inspection.

49. (canceled)

1           50. (previously presented) The method defined in claim  
2 30, further comprising the step of  
3 releasably adhering a mounting strip to outer faces of  
4 the strip sections turned away from the antenna strip and to  
5 exposed portions of the antenna strip between adjacent film  
6 sections.

1           51. (previously presented) The method defined in claim  
2 30 wherein the module is associated with two respective module  
3 contacts and the module is secured to the film between the two  
4 respective contacts.

1                   52. (previously presented) The method defined in claim  
2   30 wherein the film strip is flexible and of plastic.

1                   53. (new) The method defined in claim 30, further  
2   comprising the step of  
3                   releasably adhering a mounting strip to a face of the  
4   antenna strip turned away from the module strip.